



Specification for Approval

Date: 2018/9/12

HCB3216KF-121T60







Customer	:	深圳臺慶
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TAI-TECH P/N:

	CUSTOMER P/N:					
	DESCRIPTION:					
	QUANTITY:	pcs	<u>.</u>			
REM	MARK:					
	Cu	stomer Approval Feedba	nck			

西北臺慶科技股份有限公司 TAI-TECH Advanced Electronics Co., Ltd

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High Current Ferrite Chip Bead(Lead Free)

HCB3216KF-121T60

REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWI
1.0	13/06/06	變更可靠度條件	楊祥忠	羅培君	張嘉珩
2.0	14/01/24	變更電鍍錫層厚度 3.0um min.=>3.5um min.	楊祥忠	羅培君	張嘉玲
3.0	14/08/01	變更 Reflow 圖示	楊祥忠	羅培君	張嘉玲
3.1	14/08/01	修正包裝帶尺寸	楊祥忠	羅培君	張嘉玲
4.0	16/01/26	增訂可靠度 Thermal shock: (Bead) Step3:125±2℃ 30±5min	楊祥忠	詹偉特	張嘉玲
5.0	17/02/16	修訂 Recommended PC Board Pattern	楊祥忠	詹偉特	張嘉玲
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TAI-TECH KBM01-180900264 P2.

High Current Ferrite Chip Bead(Lead Free)

HCB3216KF-121T60

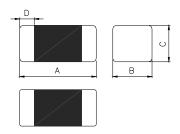
Certificate

Green Partner

1.Features

- 1. Monolithic inorganic material construction.
- 2. Closed magnetic circuit avoids crosstalk.
- 3. Suitable for reflow soldering.
- 4. Shapes and dimensions follow E.I.A. spec.
- 5. Available in various sizes.
- 6. Excellent solder ability and heat resistance.
- 7. High reliability.
- 8. 100% Lead(Pb) & Halogen-Free and RoHS compliant.
- 9. Low DC resistance structure of electrode to prevent wasteful electric power consumption.

2. Dimensions



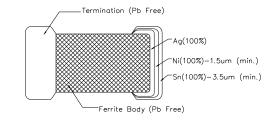
Chip Size				
Α	3.20±0.20			
В	1.60±0.20			
С	1.10±0.20			
D	0.50±0.30			

Units: mm

3.Part Numbering



F: Rated Current 60=6000m/

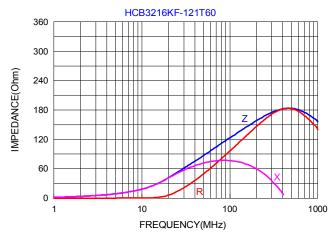


4.Specification

Tai-Tech Part Number	Impedance (Ω)	Test Frequency (Hz)	DC Resistance (Ω) max.	Rated Current (mA) max.
HCB3216KF-121T60	120±25%	60mV/100M	0.018	6000

- Rated current: based on temperature rise test
- In compliance with EIA 595

■ Impedance-Frequency Characteristics



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TAI-TECH KBM01-180900264 P3.

5. Reliability and Test Condition

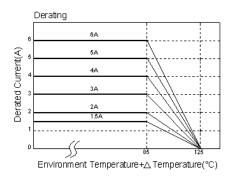
Item	Performance	Test Condition
Series No.	FCB FCM HCB GHB FCA	
Operating Temperature	-55∼+125 $^{\circ}$ C (Including self-temperature rise)	
Transportation Storage Temperature	-55~+125℃ (on board)	For long storage conditions, please see the Application Notice
Impedance (Z)	Refer to standard electrical characteristics list	Agilent4291 Agilent E4991 Agilent4287 Agilent16192
DC Resistance	Refer to standard electrical characteristics list	Agilent 4338
Rated Current		DC Power Supply Over Rated Current requirements, there will be some risk
Temperature Rise Test	Rated Current < 1A ΔT 20℃Max Rated Current ≧ 1A ΔT 40℃Max	Applied the allowed DC current. Temperature measured by digital surface thermometer.
Life test	Appearance: no damage. Impedance: within±15%of initial value. Inductance: within±10%of initial value.	Preconditioning: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profiles) Temperature: 125±2°C Applied current: rated current. Duration: 1000±12hrs. Measured at room temperature after placing for 24±2 hrs. Preconditioning: Run through IR reflow for 2
Load Humidity	Q : Shall not exceed the specification value. RDC : within ±15% of initial value and shall not exceed the specification value	times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Humidity: 85±2%R.H. Temperature: 85±2°C. Duration: 1000hrs Min. with 100% rated current. Measured at room temperature after placing for 24±2 hrs.
Thermal shock	Appearance: no damage. Impedance: within±15%of initial value. Inductance: within±10%of initial value. Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Condition for 1 cycle Step1: $-55\pm2^{\circ}$ C 30 ± 5 min. Step2: $25\pm2^{\circ}$ C 30 ± 5 min. Step3: $+125\pm2^{\circ}$ C 30 ± 5 min. Number of cycles: 500 Measured at room temperature after placing for 24 ± 2 hrs.
Vibration	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020D Classification Reflow Profiles) Oscillation Frequency: 10~2K~10Hz for 20 minutes Equipment: Vibration checker Total Amplitude:1.52mm±10% Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations) ∘
Bending	Appearance: No damage. Impedance: within±10% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within±15% of initial value and shall not exceed the specification value	Shall be mounted on a FR4 substrate of the following dimensions: >=0805inch(2012mm):40x100x1.2mm <0805inch(2012mm):40x100x0.8mm Bending depth: >=0805inch(2012mm):1.2mm <0805inch(2012mm):0.8mm Duration of 10 sec for a min.
		Test condition:
Shock	Appearance : No damage. Impedance : within±10% of initial value Inductance : within±10% of initial value	Type
	Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	SMD 50 11 Half-sine 11.3
		Lead 50 11 Half-sine 11.3
Solderability	More than 95% of the terminal electrode should be covered with solder.	Preheat: 150°C,60sec. Solder: Sn96.5%-Ag3%-Cu0.5% Solder temperature: 245±5°C Flux for lead free: Rosin. 9.5% Depth: completely cover the termination. Dip time: 4±1sec.

TAI-TECH KBM01-180900264 P4.

Item	Performance			Test Condition	
			Number of heat	cycles: 1	
Resistance to Soldering	Appearance: No damage. Impedance: within±15% of initial value			Time (s)	Temperature ramp/immersion and emersion rate
Heat	Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	
			Depth: complete	ly cover th	ne termination
Terminal strength	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within±15% of initial value and shall not exceed the specification value	times.(IPC/JED Reflow Profiles) Component mou >0805inch(2012 <=0805inch(201 to the side of a of shall be applied	unted on a mm):1kg 2mm):0.5 device bei I for 60 +	ng tested. This force 1 seconds. Also the dually as not to shock	

**Derating Curve

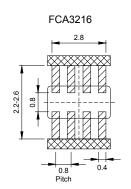
For the ferrite chip bead which withstanding current over 1.5A, as the operating temperature over $85^{\circ}\mathrm{C}$, the derating current information is necessary to consider with. For the detail derating of current, please refer to the Derated Current vs. Operating Temperature curve.



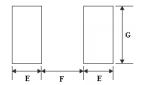
6. Soldering and Mounting

6-1. Recommended PC Board Pattern

Chip Size							Pattern ow Sold	• • • •																																
Series	Type	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	F(mm)	G(mm)																																
	0603	0.6±0.03	0.30±0.03	0.30±0.03	0.15±0.05	0.35	0.30	0.40																																
FCB	1005	1.0±0.10	0.50±0.10	0.50±0.10	0.25±0.10	0.50	0.40	0.60																																
FCM	1608	1.6±0.15	0.80±0.15	0.80±0.15	0.30±0.20	0.80	0.85	0.95																																
HCB	2012	2.0±0.20	1.25±0.20	0.85±0.20	0.50±0.30	1.05	5 1.00	1.45																																
GHB	2012	2.0±0.20	1.25±0.20	1.25±0.20	0.50±0.30		1.05		1.03			1.05	1.03	1.03	1.03		1.05	1.05	1.05	1.05	1.05	1.05	1.05	1.05			1.05	1.05	1.05	1.05	1.05	1.05	1.05	1.05	1.05	1.05	1.05	1.05	1.03	1.05
FCI	<mark>3216</mark>	3.2±0.20	1.60±0.20	1.10±0.20	0.50±0.30	<mark>1.05</mark>	<mark>2.20</mark>	<mark>1.80</mark>																																
FHI FCH	3225	3.2±0.20	2.50±0.20	1.30±0.20	0.50±0.30	1.05	2.20	2.70																																
HCI	4516	4.5±0.20	1.60±0.20	1.60±0.20	0.50±0.30	1.05	3.30	1.80																																
1101	4532	4.5±0.20	3.20±0.20	1.50±0.20	0.50±0.30	1.05	3.30	3.40																																



Land
Solder Resist



PC board should be designed so that products can prevent damage from mechanical stress when warping the board.

6-2. Soldering

Mildly activated rosin fluxes are preferred. The terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools. Note.

If wave soldering is used ,there will be some risk.

Re-flow soldering temperatures below 240 degrees, there will be non-wetting risk

TAI-TECH KBM01-180900264 P5.

6-2.1 Lead Free Solder re-flow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1. (Refered to J-STD-020C)

6-2.2 Soldering Iron:

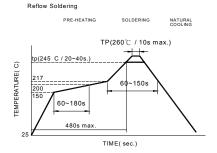
Products attachment with a soldering iron is discouraged due to the inherent process control limitations. If a soldering iron must be employed the following precautions are recommended. for Iron Soldering in Figure 2.

• 350 $^{\circ}$ C tip temperature (max)

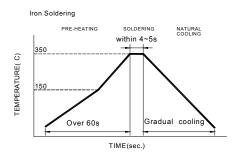
Never contact the ceramic with the iron tip

• 1.0mm tip diameter (max)

- Use a 20 watt soldering iron with tip diameter of 1.0mm
- Limit soldering time to 4~5sec.



Reflow times: 3 times max Fig.1



Iron Soldering times: 1 times max

6-2.3 Solder Volume:

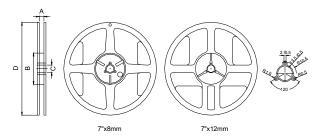
Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance. Solder shall be used not to be exceed as shown in right side:

Minimum fillet height = soldering thickness + 25% product height



7. Packaging Information

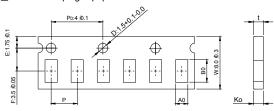
7-1. Reel Dimension



Туре	A(mm)	B(mm)	C(mm)	D(mm)
<mark>7"x8mm</mark>	9.0±0.5	60±2	13.5±0.5	<mark>178±2</mark>
7"x12mm	13.5±0.5	60±2	13.5±0.5	178±2

7-2.1 Tape Dimension / 8mm

■Material of taping is paper



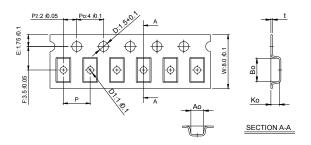
	P22.0.1 P04.0.1 01.0001.000	
Ø.1 E:1.75.90.1		
F:3.5.0.1	P	Ко

Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
060303	0.70±0.06	0.40±0.06	0.45max	2.0±0.05	0.45max
100505	1.12±0.03	0.62±0.03	0.60±0.03	2.0±0.05	0.60±0.03

Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
160808	1.80±0.05	0.96+0.05/-0.03	0.95±0.05	4.0±0.10	0.95±0.05
201209	2.10±0.05	1.30±0.05	0.95±0.05	4.0±0.10	0.95±0.05

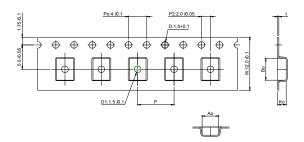
TAI-TECH KBM01-180900264 P6.

■Material of taping is plastic



Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
201212	2.10±0.10	1.28±0.10	1.28±0.10	4.0±0.10	0.22±0.05	1.0±0.10
<mark>321611</mark>	3.35±0.10	1.75±0.10	1.25±0.10	<mark>4.0±0.10</mark>	0.23±0.05	1.0±0.10
322513	3.42±0.10	2.77±0.10	1.55±0.10	4.0±0.10	0.22±0.05	1.0±0.10
321609	3.40±0.10	1.77±0.10	1.04±0.10	4.0±0.10	0.22±0.05	1.0±0.10

7-2.2 Tape Dimension / 12mm

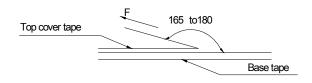


Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
451616	4.70±0.10	1.75±0.10	1.75±0.10	4.0±0.10	0.24±0.05	1.5±0.10
453215	4.70±0.10	3.45±0.10	1.60±0.10	8.0±0.10	0.24±0.05	1.5±0.10

7-3. Packaging Quantity

Chip Size	453215	451616	322513	<mark>321611</mark>	321609	201212	201209	160808	100505	060303
Chip / Reel	1000	2000	2500	<mark>3000</mark>	3000	2000	4000	4000	10000	15000
Inner box	4000	8000	12500	<mark>15000</mark>	15000	10000	20000	20000	50000	75000
Middle box	20000	40000	62500	<mark>75000</mark>	75000	50000	100000	100000	250000	375000
Carton	40000	80000	125000	<mark>150000</mark>	150000	100000	200000	200000	500000	750000

7-4. Tearing Off Force



The force for tearing off cover tape is 15 to 60 grams in the arrow direction under the following conditions.

Room Temp.	Room Humidity	Room atm	Tearing Speed
(℃)	(%)	(hPa)	mm/min
5~35	45~85	860~1060	300

Application Notice

Storage Conditions(component level)

To maintain the solder ability of terminal electrodes:

- 1. TAI-TECH products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 2. Temperature and humidity conditions: Less than 40°C and 60% RH.
- 3. Recommended products should be used within 12 months from the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
- 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
- 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.



Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 1 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

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(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R., CHINA)

以下測試樣品係由申請廠商所提供及確認 (The following sample(s) was/were submitted and identified by/on behalf of the applicant as):

樣品名稱(Sample Description)

: FERRITE CHIP BEAD INDUCTOR ARRAY MCF MCM YMV SERIES

樣品型號(Style/Item No.)

FERRITE CHIP BEAD INDUCTOR ARRAY MCF MCM YMV SERIES

收件日期(Sample Receiving Date)

2017/12/05

測試期間(Testing Period)

2017/12/05 TO 2017/12/12

測試結果(Test Results) :

請參閱下一頁 (Please refer to following pages).

Signed for and on being SGS TAIWAN LTD. Chemical Laboratory - Taipei

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Test Report

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頁數(Page): 2 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(慶邦電子元器件 (泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

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(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

測試結果(Test Results)

測試部位(PART NAME)No.1

: 整體混測(MIXED ALL PARTS)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result) No.1
鍋 / Cadmium (Cd)	mg/kg	參考IEC 62321-5 (2013),以感應耦合 電漿原子發射光譜儀檢測. / With reference to IEC 62321-5 (2013) and performed by ICP-AES.	2	n. d.
鉛 / Lead (Pb)	mg/kg	参考IEC 62321-5 (2013),以感應耦合 電漿原子發射光譜儀檢測. / With reference to IEC 62321-5 (2013) and performed by ICP-AES.	2	n. d.
汞 / Mercury (Hg)	mg/kg	参考IEC 62321-4 (2013),以感應耦合 電漿原子發射光譜儀檢測. / With reference to IEC 62321-4 (2013) and performed by ICP-AES.	2	n. d.
六價絡 / Hexavalent Chromium Cr(VI) (◆)	mg/kg	参考IEC 62321-7-2 (2017),以UV-VIS 檢測;参考IEC 62321-5 (2013),以 ICP-AES檢測. / With reference to IEC 62321-7-2 (2017) and performed by UV-VIS.; With reference to IEC 62321-5 (2013) and performed by ICP-AES.	8	n. d.
銻 / Antimony (Sb)	mg/kg	参考US EPA 3052 (1996),以感應耦合 電漿原子發射光譜儀檢測. / With reference to US EPA 3052 (1996). Analysis was performed by ICP-AES.	2	n. d.

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Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 3 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO, LTD.)

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測試項目 (Test Items)	單位 (Unit)	测試方法 (Method)	方法偵測 極限值 (MDL)	結果 (Result) No.1
砷 / Arsenic (As)	mg/kg	参考US EPA 3052 (1996),以感應耦合電漿原子發射光譜儀檢測. / With reference to US EPA 3052 (1996). Analysis was performed by ICP-AES.	2	n. d.
皴 / Beryllium (Be)	mg/kg	参考US EPA 3052 (1996),以感應耦合 電漿原子發射光譜儀檢測. / With reference to US EPA 3052 (1996). Analysis was performed by ICP-AES.	2	n. d.
全氟辛烷磺酸 / Perfluorooctane sulfonates (PFOS-Acid, Metal Salt, Amide)	mg/kg	参考US EPA 3550C (2007),以液相層 析/質譜儀檢測. / With reference to US EPA 3550C (2007). Analysis was performed by LC/MS.	10	n, d,
全氟辛酸 / PFOA (CAS No.: 335-67-1)	mg/kg	參考US EPA 3550C (2007),以液相層 析/質譜儀檢測. / With reference to US EPA 3550C (2007). Analysis was performed by LC/MS.	10	n. d.
聚氯乙烯 / PVC	**	以紅外光譜分析及焰色法檢測. / Analysis was performed by FTIR and FLAME Test.	_	Negative
鄰苯二甲酸丁苯甲酯 / BBP (Butyl Benzyl phthalate) (CAS No.: 85-68-7)	mg/kg	# HDC 60001 0 (0017)	50	n, d.
鄰苯二甲酸二丁酯 / DBP (Dibuty1 phthalate) (CAS No.: 84-74-2)	mg/kg	参考IEC 62321-8 (2017),以氣相層析 儀/質譜儀檢測. / With reference to IEC 62321-8 (2017). Analysis was	50	n. d.
鄰苯二甲酸二 (2-乙基己基)酯 / DEHP (Di- (2-ethylhexyl) phthalate) (CAS No.: 117-81-7)	mg/kg	performed by GC/MS.	50	n. d.

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Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 4 of 16

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測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result) No.1
鄰苯二甲酸二異丁酯 / DIBP (Di- isobutyl phthalate) (CAS No.: 84-69- 5)	mg/kg		50	n. d.
鄰苯二甲酸二異癸酯 / DIDP (Di- isodecyl phthalate) (CAS No.: 26761- 40-0; 68515-49-1)	mg/kg		50	n. d.
鄰苯二甲酸二異壬酯 / DINP (Di- isononyl phthalate) (CAS No.; 28553- 12-0; 68515-48-0)	mg/kg	參考IEC 62321-8 (2017),以氣相層析 儀/質譜儀檢測. / With reference to IEC 62321-8 (2017). Analysis was	50	n. d.
鄰苯二甲酸二正辛酯 / DNOP (Di-n-octyl phthalate) (CAS No.: 117-84-0)	mg/kg	performed by GC/MS.	50	n. d.
鄰苯二甲酸二正己酯 / DNHP (Di-n-hexyl phthalate) (CAS No.: 84-75-3)	mg/kg		50	n. d.
鄰苯二甲酸二戊酯 / Di-n-pentyl phthalate (CAS No.: 131-18-0)	mg/kg		50	n. d.
六溴環十二烷及所有主要被辨別出的異構物 / Hexabromocyclododecane (HBCDD) and all major diastereoisomers identified (α - HBCDD, β - HBCDD, γ - HBCDD) (CAS No.: 25637-99-4 and 3194-55-6 (134237-51-7, 134237-50-6, 134237-52-8))	mg/kg	参考IEC 62321 (2008),以氣相層析/ 質譜儀檢測. / With reference to IEC 62321 (2008). Analysis was performed by GC/MS.	5	n. d.

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Test Report

號碼(No.): CE/2017/C0633 日期(Date): 2017/12/12

頁數(Page): 5 of 16

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測試項目 (Test Items)	單位 (Unit)	测試方法 (Method)	方法偵測 極限值 (MDL)	結果 (Result) No.1
多溴聯苯總和 / Sum of PBBs	mg/kg			n. d.
一溴聯苯 / Monobromobiphenyl	mg/kg	Ī	5	n. d.
二溴聯苯 / Dibromobiphenyl	mg/kg	Ι Γ	5	n, d.
三溴聯苯 / Tribromobiphenyl	mg/kg	1 Γ	5	n, d,
四溴聯苯 / Tetrabromobiphenyl	mg/kg]	5	n, d,
五溴聯苯 / Pentabromobiphenyl	mg/kg		5	n. d.
六溴聯苯 / Hexabromobiphenyl	mg/kg		5	n. d.
七溴聯苯 / Heptabromobiphenyl	ng/kg		5	n. d.
八溴聯苯 / Octabromobiphenyl	mg/kg		5	n, d.
九溴聯苯 / Nonabromobiphenyl	mg/kg	】参考IEC 62321-6 (2015),以氣相層析 □	5	n. d.
十溴聯苯 / Decabromobiphenyl	mg/kg	/質譜儀檢測. / With reference to	5	n. d.
多溴聯苯醚總和 / Sum of PBDEs	mg/kg	IEC 62321-6 (2015) and performed	***	n, d.
一溴聯苯醚 / Monobromodiphenyl ether	mg/kg	by GC/MS.	5	n. d.
二溴聯苯醚 / Dibromodiphenyl ether	mg/kg		5	n. d.
三溴聯苯醚 / Tribromodiphenyl ether	ng/kg		5	n. d.
四溴聯苯醚 / Tetrabromodiphenyl ether	mg/kg		5	n, d.
五溴聯苯醚 / Pentabromodiphenyl ether	mg/kg		5	n. d.
六溴聯苯醚 / Hexabromodiphenyl ether	mg/kg		5	n. d.
七溴聯苯醚 / Heptabromodiphenyl ether	mg/kg]	5	n. d.
八溴聯苯醚 / Octabromodiphenyl ether	mg/kg	Ι	5	n. d.
九溴聯苯醚 / Nonabromodiphenyl ether	mg/kg] Γ	5	n, d,
十溴聯苯醚 / Decabromodiphenyl ether	mg/kg		5	n. đ.

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號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 6 of 16

Test Report

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测試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result) No.1
鹵素 / Halogen			· · · · · · · · · · · · · · · · · · ·	NO. 1
鹵素(氟)/ Halogen-Fluorine (F) (CAS No.: 14762-94-8)	mg/kg		50	n. d.
鹵素(氯)/ Halogen-Chlorine (C1) (CAS No.: 22537-15-1)	mg/kg	参考BS EN 14582 (2016),以離子層析 儀分析. / With reference to BS EN	50	n. d.
鹵素(溴)/ Halogen-Bromine (Br) (CAS No.: 10097-32-2)	mg/kg	14582 (2016). Analysis was performed by IC.	50	n. d.
鹵素(碘)/ Halogen-Iodine(I)(CAS No.: 14362-44-8)	mg/kg		50	n, d.

備註(Note):

- 1. mg/kg = ppm ; 0.1wt% = 1000ppm
- 2. n.d. = Not Detected (未檢出)
- 3. MDL = Method Detection Limit (方法偵測極限值)
- 4. "-" = Not Regulated (無規格值)
- 5. **= Qualitative analysis (No Unit) 定性分析(無單位)
- 6. Negative = Undetectable 陰性(未偵測到); Positive = Detectable 陽性(已偵測到)

7. (�):

若鉻含量小於六價鉻之方法偵測極限值,則六價鉻為n,d,,不須再測試六價鉻。

The result of Cr(VI) is "n.d." as the result of Chromium (Cr) is less than the MDL of Cr(VI), and confirmation test of Cr(VI) is not required.

若鉻含量未小於六價鉻之方法偵測極限值,需進行六價鉻測試。

If the Chromium (Cr) content is not less than the MDL of Cr(VI), confirmation test of Cr(VI) is required.

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Test Report

號碼(No.): CE/2017/C0633 日期(Date): 2017/12/12

頁數(Page): 7 of 16

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8. 樣品的測試是基於申請人要求混合測試,報告中的混合測試結果不代表其中個別單一材質的含量. (The samples was/were analyzed on behalf of the applicant as mixing sample in one testing. The above results was/were only given as the informality value.)

PFOS參考資訊(Reference Information): 持久性有機污染物 POPs - (EU) 757/2010

PFOS濃度在物質或製備中不得超過0.001%(10ppm),在半成品、成品或零部件中不得超過0.1%(1000ppm),在紡織品或塗 層材料中不得超過1ug/m2。

(Outlawing PFOS as substances or preparations in concentrations above 0.001% (10ppm), in semi-finished products or articles or parts at a level above 0.1%(1000ppm), in textiles or other coated materials above lug/m^2 .)

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Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 8 of 16

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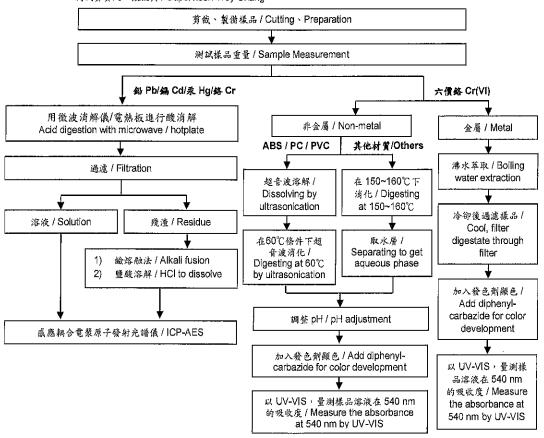
(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R, CHINA)

<u>重金屬流程圖 / Analytical flow chart of Heavy Metal</u>

根據以下的流程圖之條件,樣品已完全溶解。(六價鉻測試方法除外)

These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr6+ test method excluded)

- 測試人員:王志瑋 / Technician : JR Wang
- 测試負責人:張啟興 / Supervisor: Troy Chang



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Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 9 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

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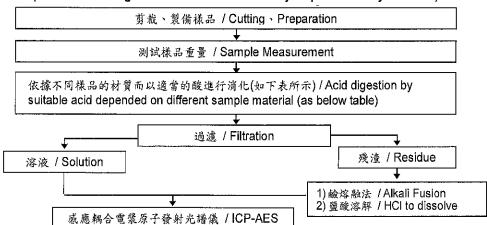
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根據以下的流程圖之條件,樣品已完全溶解。 / These samples were dissolved totally by pre-conditioning method according to below flow chart.

- 測試人員:王志瑋 / Technician: JR Wang
- 測試負責人:張啟興 / Supervisor: Troy Chang

元素以 ICP-AES 分析的消化流程圖 (Flow Chart of digestion for the elements analysis performed by ICP-AES)



	_
鋼,銅,鋁,焊錫 / Steel, copper, aluminum, solder	王水,硝酸,鹽酸,氫氟酸,雙氧水 /
	Aqua regia, HNO₃, HCl, HF, H₂O₂
玻璃 / Glass	硝酸,氫氟酸 / HNO3/HF
金,鉑,鈀,陶瓷 / Gold, platinum, palladium, ceramic	王水 / Aqua regia
銀 / Silver	硝酸 / HNO3
塑膠 / Plastic	硫酸,雙氧水,硝酸,鹽酸 / H2SO4, H2O2, HNO3, HCI
其他 / Others	加入適當的試劑至完全溶解 / Added appropriate
	reagent to total digestion

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Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 10 of 16

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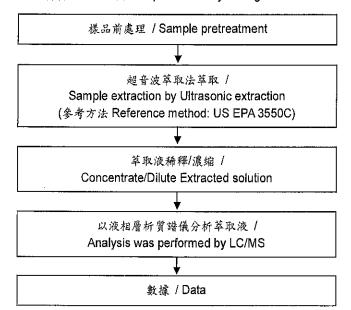
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全氟辛酸/全氟辛烷磺酸分析流程圖 / Analytical flow chart - PFOA/PFOS

■ 測試人員:涂雅苓 / Technician: Yaling Tu

測試負責人:張啟興 / Supervisor: Troy Chang



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Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 11 of 16

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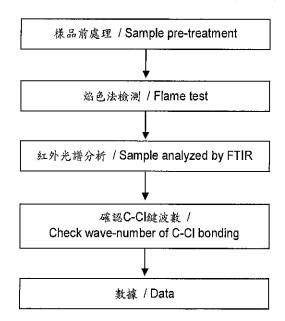
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聚氯乙烯物質判定分析流程圖 / Analysis flow chart - PVC

測試人員:涂雅苓 / Technician: Yaling Tu

測試負責人:張啟興 / Supervisor: Troy Chang



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Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 12 of 16

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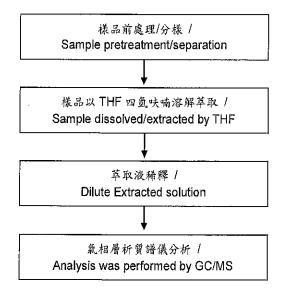
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<u>可塑劑分析流程圖 / Analytical flow chart - Phthalate</u>

測試人員:徐毓明 / Technician: Andy Hsu

測試負責人:張啟興 / Supervisor: Troy Chang

【测試方法/Test method: IEC 62321-8】



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Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 13 of 16

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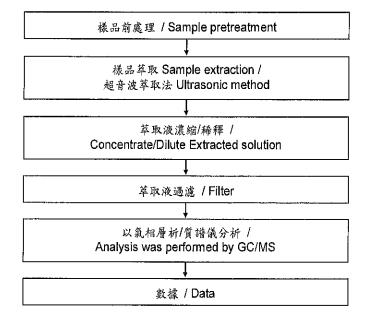
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六溴環十二烷分析流程圖 / Analytical flow chart - HBCDD

- 測試人員:涂雅苓 / Technician: Yaling Tu
- 測試負責人:張啟興 / Supervisor: Trov Chang



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Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 14 of 16

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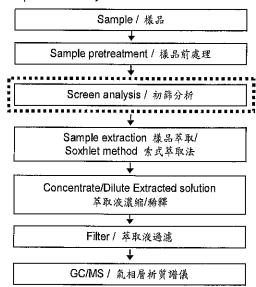
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<u>多溴聯苯/多溴聯苯醚分析流程圖 / Analytical flow chart - PBB/PBDE</u>

測試人員:涂雅苓 / Technician: Yaling Tu

測試負責人:張啟興 / Supervisor: Troy Chang

初次测試程序 / First testing process _ 選擇性篩檢程序 / Optional screen process •••••• 確認程序 / Confirmation process - - - →



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Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 15 of 16

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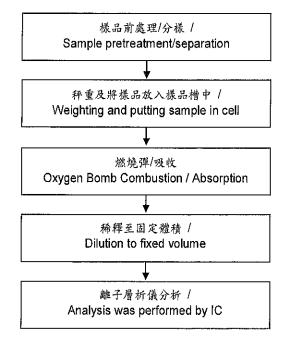
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鹵素分析流程圖 / Analytical flow chart - Halogen

測試人員: 陳恩臻 / Technician: Rita Chen

測試負責人:張啟興 / Supervisor: Troy Chang



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Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 16 of 16

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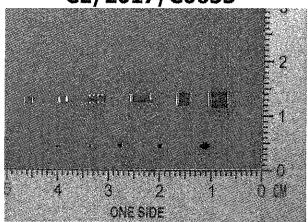
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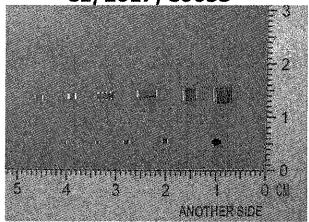
* 照片中如有箭頭標示,則表示為實際檢測之樣品/部位. *

(The tested sample / part is marked by an arrow if it's shown on the photo.)

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